电性参数

ǎ ^ Ta=25Ņ˜ Absolute Maximum Rating(ta=25 Ņ)

ǎ Parameter	ˆ Symbol	ỵ Value	ʏ β Unit
wˆ Max Power Dissipation˜	PD	75	mW
h ˆ Max Continuous Forward Current˜	IF	80	mA
ll ỵ ˆ Peak Forward Current˜	IFP	20	mA
ĩ h ʌˆ Max Reve n			

Optical-electrical paran

焊接指导（2）

Guideline for Soldering (2)

Cleaning

ضي U ą ˘ ضي Ь G 30Ņ ð Й 3 № ˘ Ь G 50Ņ ð Й

30 Â

ą Ì ɾ ³ ╕ ╠˘ ѽ ą ╕ Ь Ψ LED ė № ᴴ Â

Ӟ ˘ ѿ ѡ Ь 300W˘ ϒ ↕˜ LED ᴴ Â

Í ᵣ ' ѽ ð ϒ Ψ LED ᴴ Â

It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go under 30Ņ for 3 utes or 50 or 30 s ds. When ng other sol ents, it ld be co d beforehand whether the s ents will c ve th ckage and th sin or not.

Ultrasonic leaning i lso effective w for eaning. But e influen of Ultra c cleaning fac such as ultra c power. Generally, th trase po sho not be higher than 300W. Befor eaning, retest shou e done to onfirm whether any damage to LEDs will occur.

✱ **注意：** ѿ ʌ ↕ Ь G PCB ė Â Í ᵣ Ĩ ⌠ ج ڑ˘ PCB ė Â

✱ **Note:** This general guideline may not apply to all PCB designs and configurations of all soldering equipment. The technics in practise is inf